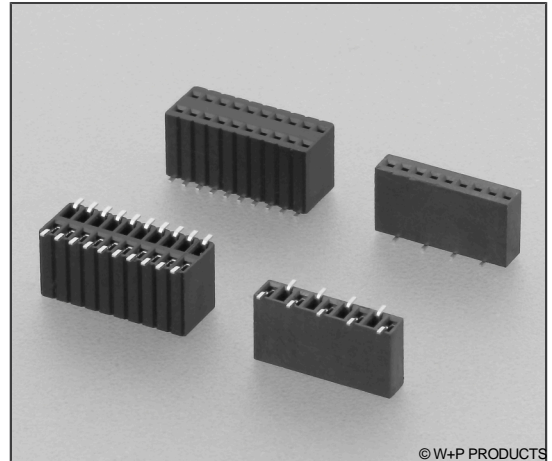


46-7110 Economy Version

SMT-Buchsenleisten RM 1,27x2,54mm, stehend, 1-/2-reihig
SMT Female Headers, 1.27x2.54mm Pitch, Vertical, Single/Double Row

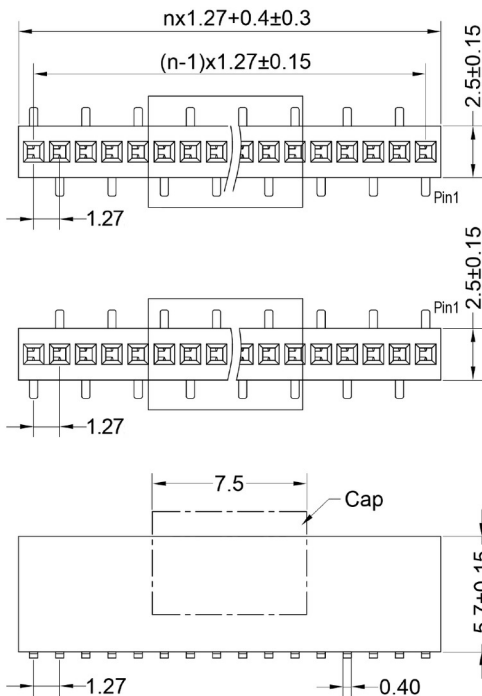
Technische Daten / Technical Data

Isolierkörper <i>Insulator</i>	Thermoplast, nach UL94 V-0 <i>Thermoplastic, rated UL94 V-0</i>
Kontaktmaterial <i>Contact Material</i>	Kupferlegierung <i>Copper alloy</i>
Kontaktoberfläche <i>Contact Surface</i>	Au über Ni <i>Au over Ni</i>
Durchgangswiderstand <i>Contact Resistance</i>	< 20 mΩ
Isolationswiderstand <i>Insulation Resistance</i>	> 1000 MΩ
Spannungsfestigkeit <i>Test Voltage</i>	500 V AC/DC
Nennstrom <i>Current Rating</i>	1 A
Temperaturbereich <i>Temperature Range</i>	-40 °C ~ +105 °C
Verarbeitung <i>Processing</i>	260 °C für 10 sec. / 230 °C für 30-60 sec. 260 °C for 10 sec. / 230 °C for 30-60 sec.

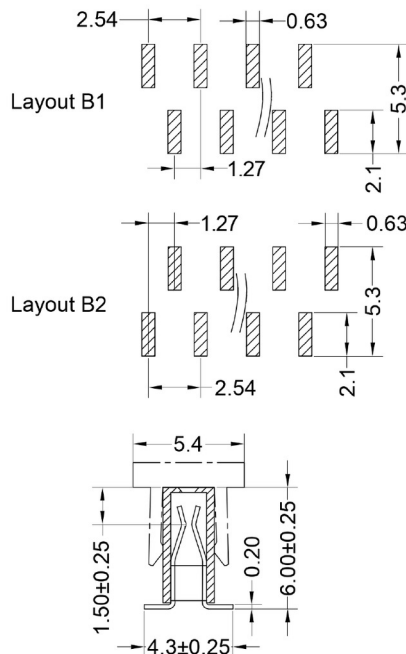


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Geeignet für 0,46mm Vierkantstifte
Mates with 0.46mm square pins



Recommended PCB Layouts (Top Side)
(PCB BOARD TOLERANCE ±0.05)

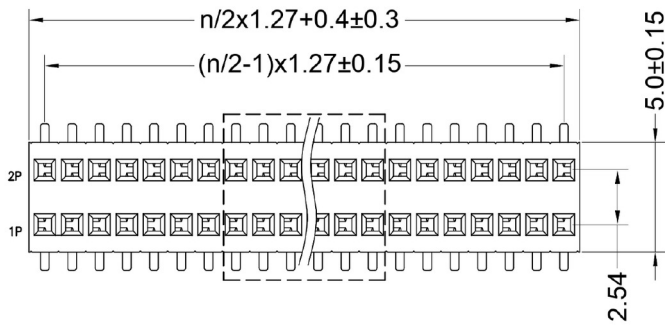


Series	Contacts*	Rows*	Plating	Locating Pegs	Packaging*
46-7110	014 003-030 Einreihig Single row	1 1 Einreihig, Layout B1 Single row, layout B1 2 Einreihig, Layout B2 Single row, layout B2	00 00 Vergoldet Gold plated	00 00 Ohne Positionierhilfe W/o locating pegs	ST ST PPST PPTR

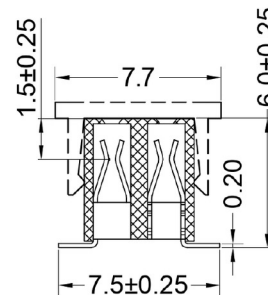
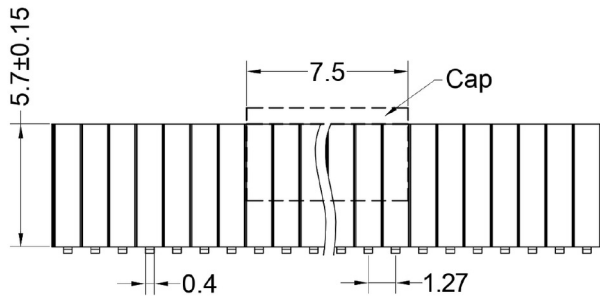
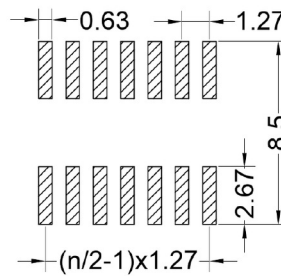
46-7110 Economy Version

SMT-Buchsenleisten RM 1,27x2,54mm, stehend, 1-/2-reihig

SMT Female Headers, 1.27x2.54mm Pitch, Vertical, Single/Double Row



Recommended PCB Layouts (Top Side)
(PCB BOARD TOLERANCE ±0.05)



Series	Contacts*	Rows	Plating	Locating Pegs	Packing*
46-7110	044 004-080 Zweireihig Double row	3 3 Zweireihig Double row	00 00 Vergoldet Gold plated	00 00 Ohne Positionierhilfe W/o locating pegs	PPST ST PPST PPTR

* Dies ist ein **Bestellbeispiel** -
bitte durch Ihre Spezifikationen ersetzen.
* This is an **order example** -
please replace by your specifications.

Lieferformen / Packaging Options:

ST In Stangen ohne Pick&Place-Pads / In tubes w/o Pick&Place-Pads

PPST In Stangen mit P&P-Pads / In tubes with P&P-Pads

PPTR Tape & Reel mit P&P-Pads / Tape & Reel with P&P-Pads

Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum T_{Smin}	150 °C
Temperatur Maximum T_{Smax}	200 °C
Dauer $T_{Smin} - T_{Smax}$	60 – 180s
Temperatur Lötbereich T_L	untere Temperaturangabe [°C]
Verweildauer oberhalb T_L	laut Angabe im Datenblatt [sec]
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Höchsttemperatur T_P	obere Temperaturangabe [°C]
Dauer Höchsttemperatur	laut Angabe im Datenblatt [sec]
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Dauer 25 °C – Höchsttemperatur T_P	max. 8m

Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature T_{Smin}	150 °C
Maximum Temperatur T_{Smax}	200 °C
Duration $T_{Smin} - T_{Smax}$	60 – 180s
Soldering Range Temperature T_L	Lower Temperature [°C]
Duration above T_L	Acc. to datasheet [sec]
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Peak Temperature T_P	Upper Temperature [°C]
Duration Peak Temperature	Acc. to datasheet [sec]
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Duration 25°C - Peak Temp. T_P	max. 8min

